

Title (en)

CORROSION AND MOISTURE RESISTANT COPPER BASED BONDING WIRE COMPRISING NICKEL

Title (de)

KORROSIONS- UND FEUCHTIGKEITSBESTÄNDIGER AUF BONDDRAHT AUF KUPFERBASIS MIT NICKEL

Title (fr)

FIL DE CONNEXION À BASE DE CUIVRE RÉSISTANT À L'HUMIDITÉ ET À LA CORROSION ET COMPRENANT DU NICKEL

Publication

**EP 3237645 A1 20171101 (EN)**

Application

**EP 15818103 A 20151126**

Priority

- SG 10201408586X A 20141222
- SG 2015000142 W 20151126

Abstract (en)

[origin: WO2016105276A1] A wire comprising a core comprising or consisting of (a) nickel in an amount in the range of from 0.005 to 5 wt.-%, (b) optionally, silver in an amount in the range of from 0.005 to 1 wt.-%, (c) copper in an amount in the range of from 94 wt.-% to 99.98 wt.-%, and (d) 0 to 100 wt.-ppm of further components, wherein all amounts in wt.-% and wt.-ppm are based on the total weight of the core, wherein the core has an average size of crystal grains in the range of from 1.5 to 30 µm, the average size determined according to the line intercept method, wherein the wire has an average diameter in the range of from 8 to 80 µm.

IPC 8 full level

**C22C 9/00** (2006.01); **B32B 15/01** (2006.01); **C22C 9/06** (2006.01); **C22F 1/08** (2006.01); **C23C 28/00** (2006.01)

CPC (source: EP US)

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C-Set (source: EP)

1. **H01L 2924/00014 + H01L 2224/45015 + H01L 2924/2075**
2. **H01L 2924/00014 + H01L 2224/45014 + H01L 2924/206**
3. **H01L 2224/45147 + H01L 2924/01028**
4. **H01L 2224/45147 + H01L 2924/01047**
5. **H01L 2224/45565 + H01L 2224/45147 + H01L 2224/45664**
6. **H01L 2224/45565 + H01L 2224/45147 + H01L 2224/45669**
7. **H01L 2224/45565 + H01L 2224/45147 + H01L 2224/45639**
8. **H01L 2224/45572 + H01L 2224/45147 + H01L 2224/45664 + H01L 2224/45644**
9. **H01L 2224/45572 + H01L 2224/45147 + H01L 2224/45669 + H01L 2224/45644**
10. **H01L 2224/45572 + H01L 2224/45147 + H01L 2224/45639 + H01L 2224/45644**
11. **H01L 2224/45147 + H01L 2924/01201**
12. **H01L 2924/00014 + H01L 2224/45015 + H01L 2924/20751**
13. **H01L 2224/45147 + H01L 2924/01202**
14. **H01L 2224/45147 + H01L 2924/01203**
15. **H01L 2924/00014 + H01L 2224/45015 + H01L 2924/20752**
16. **H01L 2924/00014 + H01L 2224/45015 + H01L 2924/20753**
17. **H01L 2924/00014 + H01L 2224/45015 + H01L 2924/20754**
18. **H01L 2924/00014 + H01L 2224/45015 + H01L 2924/20755**
19. **H01L 2924/00014 + H01L 2224/45015 + H01L 2924/20756**
20. **H01L 2924/00014 + H01L 2224/45015 + H01L 2924/20757**
21. **H01L 2924/00014 + H01L 2224/45015 + H01L 2924/20758**

Citation (search report)

See references of WO 2016105276A1

Designated contracting state (EPC)

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Designated extension state (EPC)

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DOCDB simple family (publication)

**WO 2016105276 A1 20160630; WO 2016105276 A8 20170629**; CN 107109532 A 20170829; EP 3237645 A1 20171101; JP 2018503743 A 20180208; SG 10201408586X A 20160728; TW 201631602 A 20160901; TW I587317 B 20170611

DOCDB simple family (application)

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